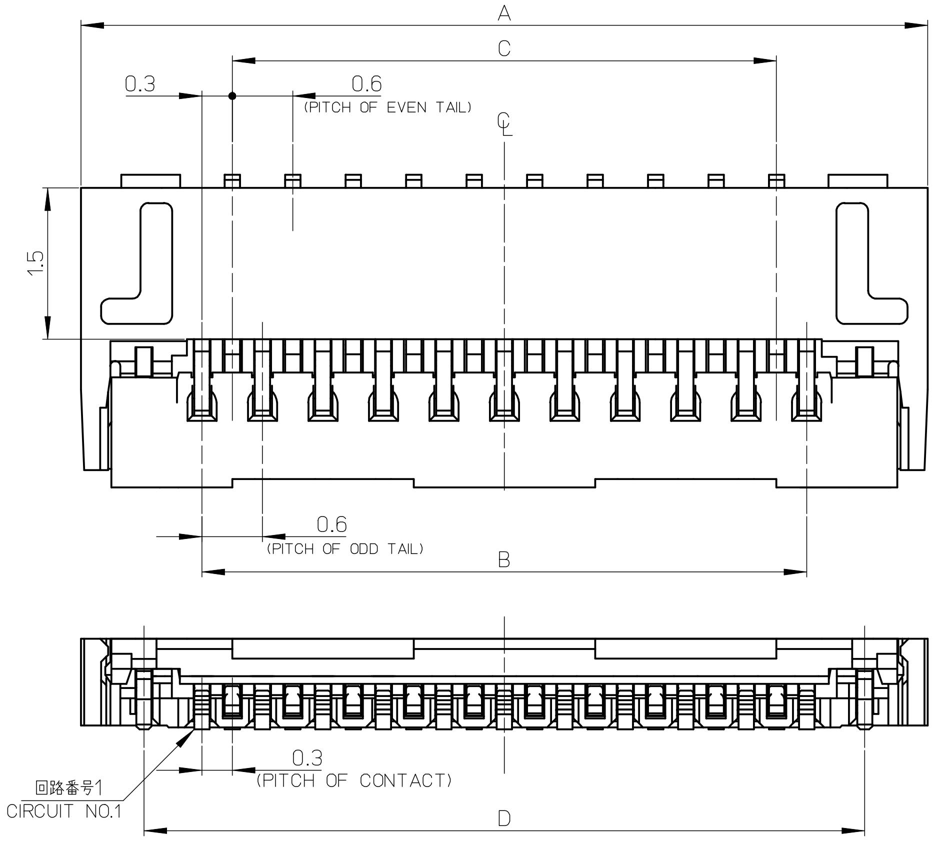
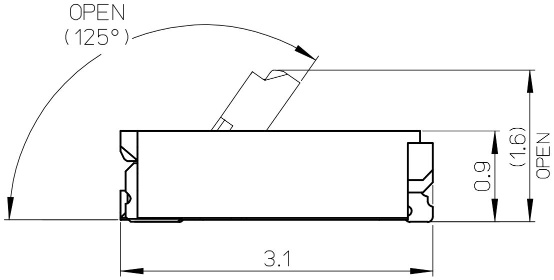


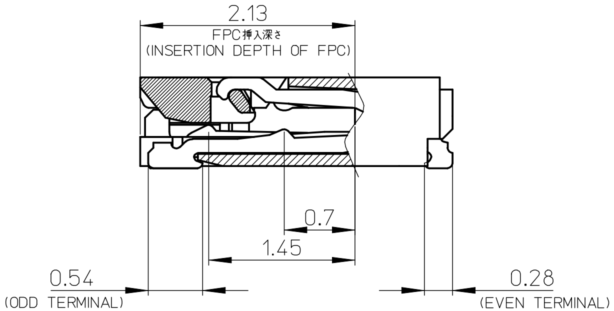
注記
NOTES:
1.材質
MATERIAL
ハウジング：LCP（液晶ポリマー）、ガラス充塡、UL94V-0
HOUSING:LCP(LIQUID CRYSTAL POLYMER),
GLASS FILLED,UL94V-0
アクチュエータ：ナイロン、ガラス充塡、UL94V-0
ACTUATOR:NYLON(POLYAMIDE),
GLASS FILLED,UL94V-0
ターミナル：銅合金（t=0.15）
TERMINAL:COPPER ALLOY(t=0.15)
金具：銅合金(t=0.15)
NAIL:COPPER ALLOY(t=0.15)

2.めっき仕様
PLATING
ターミナル
TERMINAL
部分金めっき
SEPARATED GOLD PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
金具
NAIL
錫めっき
TIN PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.
4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号ORDER No.	極 数 CIRCUITS
0.10	16.15	14.4	15	17.4	501628-5191	51
0.089	14.35	12.6	13.2	15.6	501628-4591	45
0.078	12.55	10.8	11.4	13.8	501628-3991	39
0.075	11.95	10.2	10.8	13.2	501628-3791	37
0.071	11.35	9.6	10.2	12.6	501628-3591	35
0.067	10.75	9.0	9.6	12.0	501628-3391	33
0.064	10.15	8.4	9	11.4	501628-3191	31
0.056	8.95	7.2	7.8	10.2	501628-2791	27
0.046	7.15	5.4	6	8.4	501628-2191	21
0.028	4.15	2.4	3	5.4	501628-1191	11

CONNECTOR SERIES No. 501628-**11



詳細図
CROSS SECTION
(SCALE 20:1)

REVISED
EC NO: J2010-0068
DRWN:KUSATO 2009/07/30
CH'KD:HSHIMOYAMA 2009/07/31
APPR:KMORIKAWA 2009/07/31
DESCRIPTION
L
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±1 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE
MM ONLY
SCALE
40:1
DESIGN UNITS
METRIC
THIRD ANGLE PROJECTION

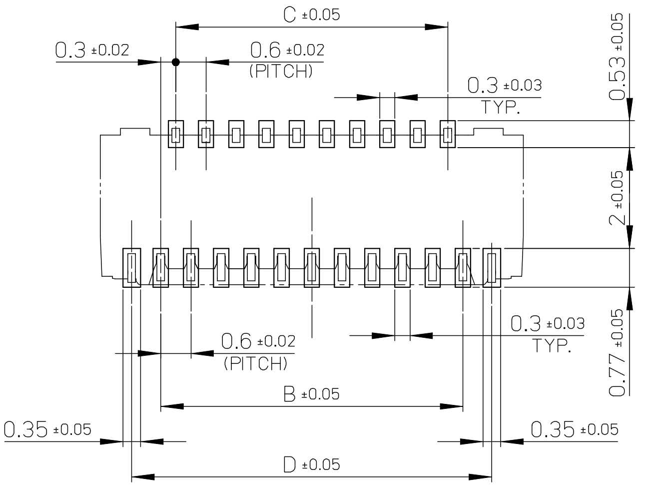
DRAWN BY HSHIMOYAMA DATE 2005/03/25
CHECKED BY HHIRATA DATE 2005/03/25
APPROVED BY MSASAO DATE 2005/03/25
MATERIAL NO.
SEE TABLE

TITLE
0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER

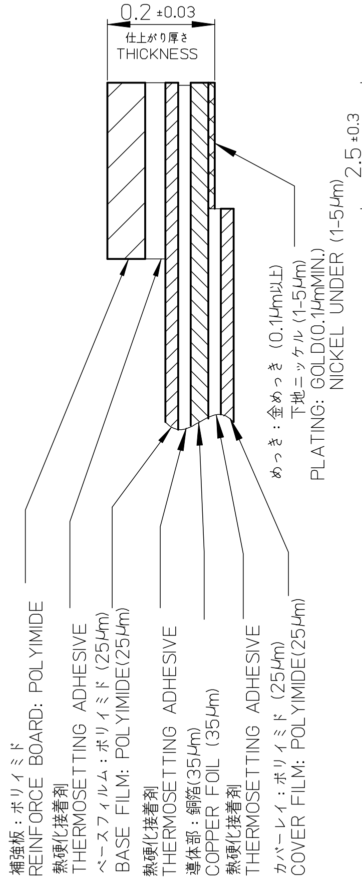
molex MOLEX INCORPORATED

DOCUMENT NO.
SD-501628-001
SHEET NO.
1 OF 2

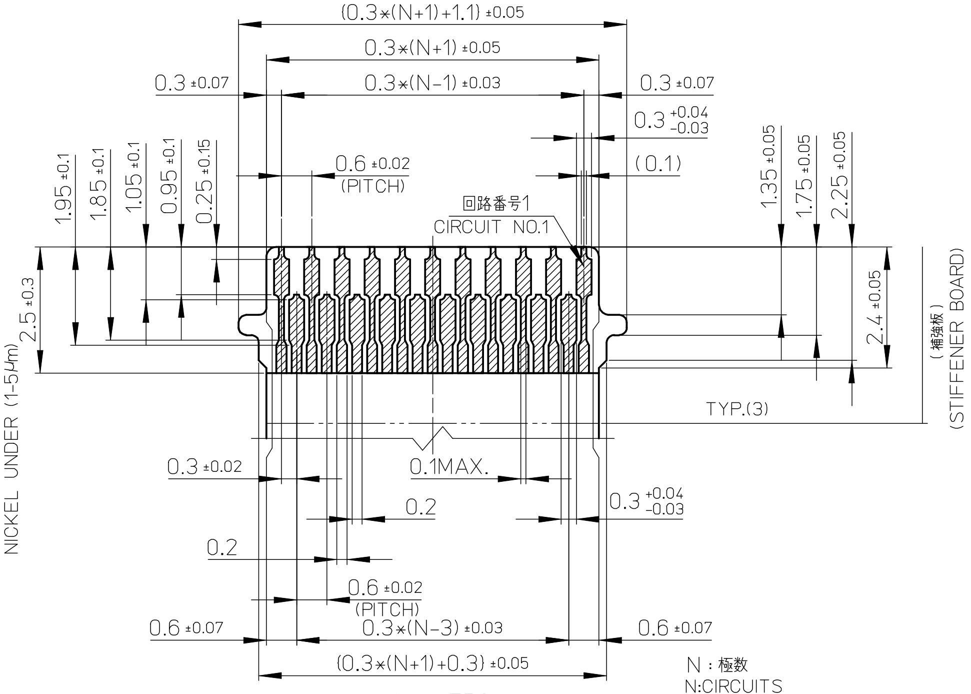
SIZE
A3



推奨基板寸法
RECOMMENDED P.C.B. PATTERN LAYOUT
(SCALE 5:1)



FPC構成推奨仕様
STRUCTURE OF FPC



N：極数
N:CIRCUITS

適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ：0.2±0.03)
(THICKNESS:0.2±0.03)

FPCについて：
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

ISO VIEW (参考)

REVISED

SEE TABLE